

# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	l <sub>D</sub>
100V	1.9mΩ@10V	245A



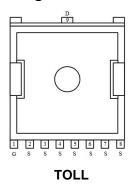
#### **Feature**

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

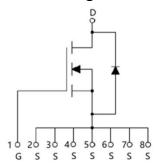
## **Applications**

- PWM Application
- Hard switched and high frequency circuits
- Power Management

### **Package**



### Circuit diagram



#### Marking



SP010N02LGHTO :Product code
\*\* :Week code

#### **Order Information**

Device	Package	Unit/Tape
SP010N02LGHTO	TOLL	2000

100V N-Channel Power MOSFET

# Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current (Tc=25°C)	I <sub>D</sub>	245	Α
Continuous Drain Current (Tc=100°C)	I <sub>D</sub>	165	Α
Pulsed Drain Current	I <sub>DM</sub>	980	Α
Single Pulse Avalanche Energy <sup>1</sup>	Eas	1296	mJ
Power Dissipation (Tc=25°C)	P <sub>D</sub>	255	W
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	0.49	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	$^{\circ}$
Operating Junction Temperature Range	TJ	-55 to 150	$^{\circ}$

# Electrical characteristics (Ta=25°C, unless otherwise noted)

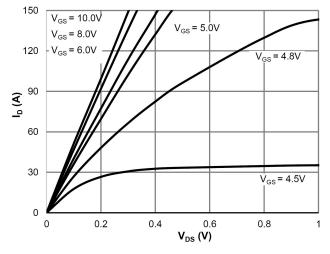
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	ID = 250μA, VGS = 0V	100	110	-	V
Drain Cut-Off Current	I <sub>DSS</sub>	VDS = 80V, VGS = 0V	-	-	1	
Gate Leakage Current	I <sub>GSS</sub>	VGS = ±20V, VDS = 0V	-	-	±0.1	μA
Gate Threshold Voltage	$V_{GS(th)}$	VDS = VGS, ID = 250µA	2.0	3.0	4.0	V
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	VGS = 10V, ID = 20A	-	1.9	2.3	mΩ
Dynamic Characteristics						
Input Capacitance	Ciss		-	8516	-	
Output Capacitance	Coss	VDS =50V, VGS = 0V, f = 1.0MHz	-	1356	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	46	-	
Total Gate Charge	Qg		-	130	-	
Gate-Source Charge	Q <sub>gs</sub>	VDS=50V , VGS=10V , ID=20A	-	56	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	37	-	
Switching Characteristics			•			
Turn-On Delay Time	t <sub>d(on)</sub>		-	42	-	
Rise Time	tr	VGS = 10V, VDS = 50V, RL=2.5Ω	-	63	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$RG = 6.0\Omega$	-	137	-	nS
Fall Time	t <sub>f</sub>		-	76	-	
Drain-Source Body Diode Characteris	stics					
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1A, VGS = 0V	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	245	Α
Reverse Recovery Time	Trr	L-204 di/dt-1004/up TI-25°C	-	107	-	nS
Reverse Recovery Charge	Qrr	I <sub>S</sub> =20A, di/dt=100A/us, TJ=25℃	-	318	-	nC

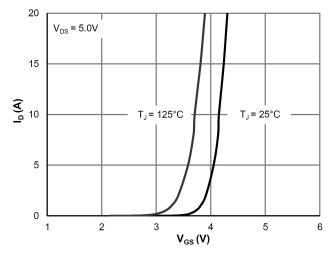
#### Note:

**1.** The test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25 $\Omega$ 



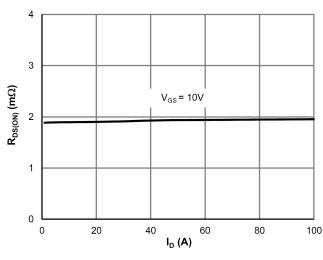
### **Typical Characteristics**

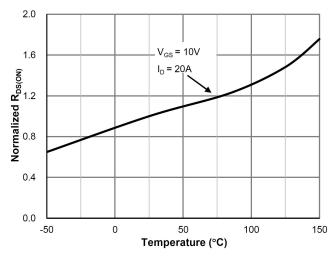






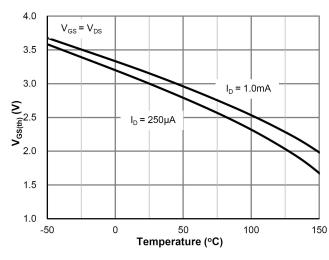


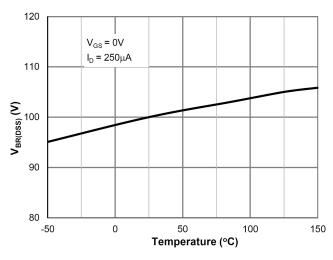




 $R_{DS(ON)}$  vs. Drain Current

 $R_{DS(ON)}$  vs. Junction Temperature

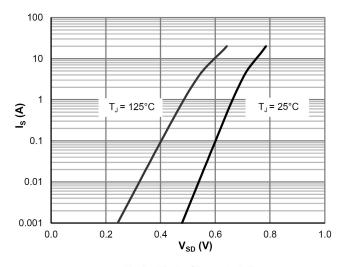


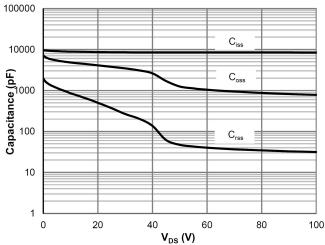


 $V_{\text{GS(th)}}$  vs. Junction Temperature

 $V_{\text{BR}(\text{DSS})}$  vs. Junction Temperature

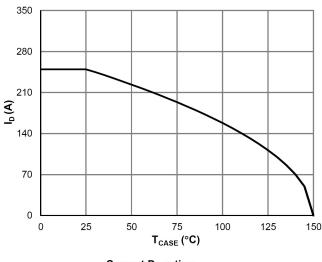


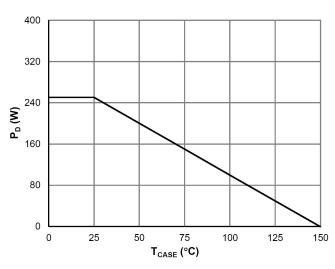




**Body-Diode Characteristics** 

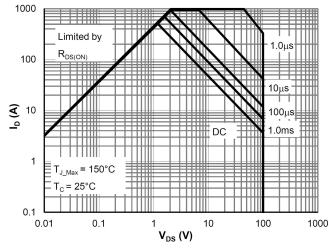
**Capacitance Characteristics** 

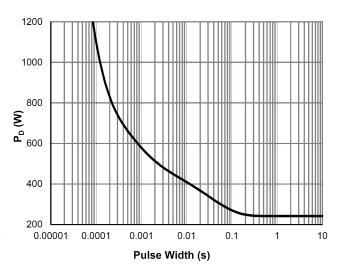




**Current De-rating** 

**Power De-rating** 

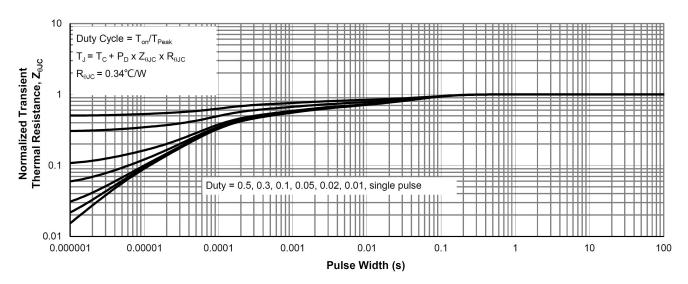




**Maximum Safe Operating Area** 

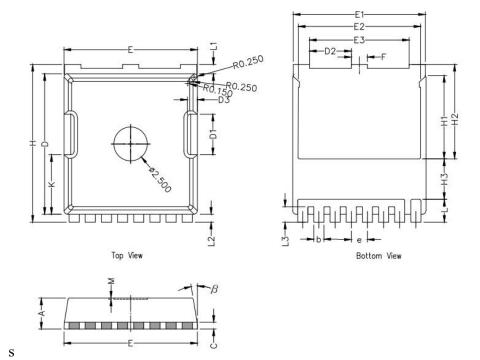
Single Pulse Power Rating, Junction-to-Case

### 100V N-Channel Power MOSFET



**Normalized Maximum Transient Thermal Impedance** 

# TOLL Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
А	2.20	2.30	2.40
b	0.65	0.75	0.85
С	0.508 REF		
D	10.25	10.40	10.55
D1	2.85	3.00	3.15
E	9.75	9.90	10.05
E1	9.65	9.80	9.95
E2	8.95	9.10	9.25
E3	7.25	7.40	7.55
е	1.20 BSC		
F	1.05	1.20	1.35
Н	11.55	11.70	11.85
H1	6.03	6.18	6.33
H2	6.85	7.00	7.15
Н3	3.00 BSC		
L	1.55	1.70	1.85
L1	0.55	0.7	0.85
L2	0.45	0.6	0.75
М	0.08 REF.		
β	8°	10°	12°
К	4.25	4.40	4.55